

SMB1N-700D-02

- High Power LED
- 700 nm, 200 mW
- SMD package, PA9T
- Dimension: 5.0 x 5.2 x 5.5 mm
- Viewing Angle: 20°

Description





Rev. A1

SMB1N-700D-02 is a surface mount AlGaInP High Power LED with a typical peak wavelength of **700 nm** and radiation of **200 mW**. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

Maximum Ratings (T_{CASE}=25°C)

Deveryoter	Ourseland	Va	1114		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	PD		1200	mW	
Forward Current	IF		500	mA	
Pulse Forward Current *1	I _{FP}		2000	mA	
Reverse Voltage	V _R		5	V	
Thermal Resistance	RTHJA		10	K/W	
Junction Temperature	T_J		120	°C	
Operating Temperature	T _{CASE}	- 40	+ 100	°C	
Storage Temperature	Tstg	- 40	+ 100	°C	
Lead Solder Temperature *2	T _{SLD}		+ 250	°C	

*1 duty=1%, pulse width = 10 μ s

*2 must be completed within 5 seconds

Electro-Optical Characteristics (T_{CASE}=25°C)

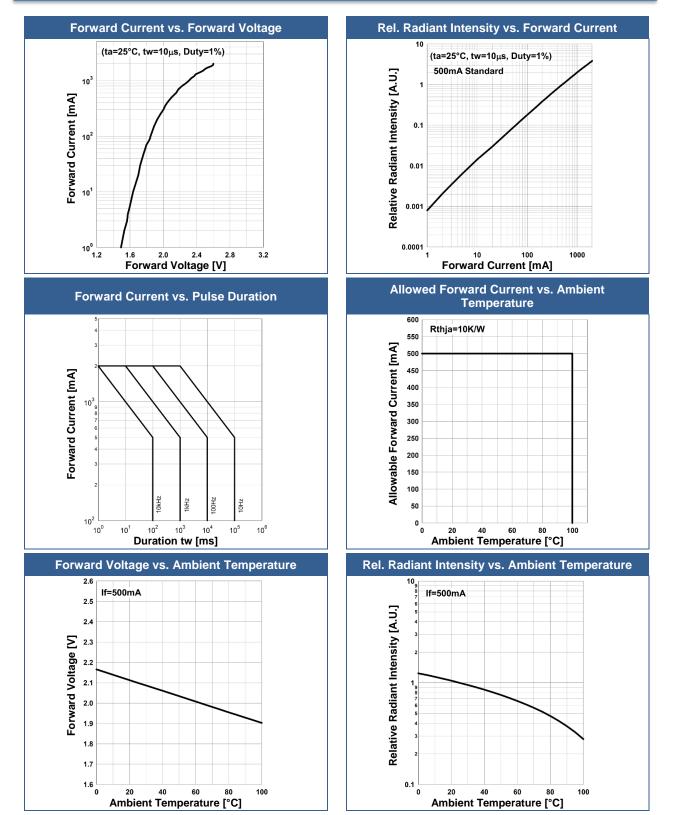
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λΡ	I⊧=500mA	690	71	710	nm
Half Width	$\Delta \lambda$	I⊧=500mA		19		nm
=	VF	I⊧=500mA		2.1	2.3	
Forward Voltage	VFP	IFP=2A		2.6		V
Radiated Power *1	Po	I _F =500mA		200		·····
Radiated Power		IFP=2A		770		mW
Dedient Internetty *2	IE	I⊧=500mA		540		
Radiant Intensity *2		IFP=2A		2000		mW/sr
Viewing Angle	φ	I _F =100mA		20		deg.
Rise Time	t _R	I⊧=500mA		40		ns
Fall Time	t⊢	IF=500mA		50		ns

*1 measured by S3584-08

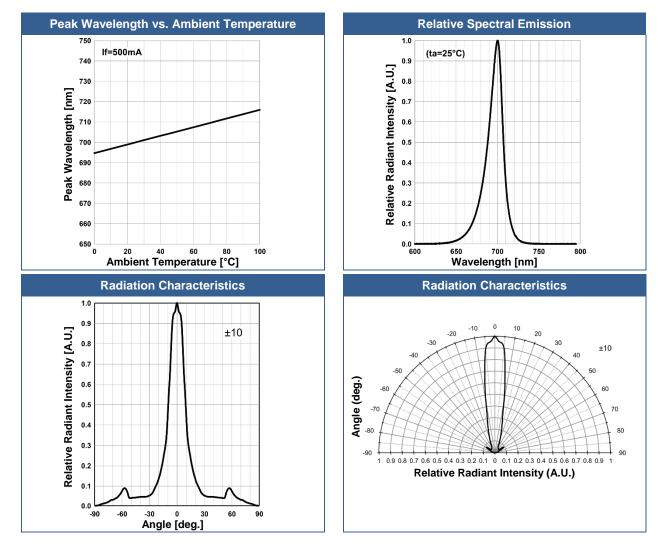
*2 measured by CIE127-2007 Condition B



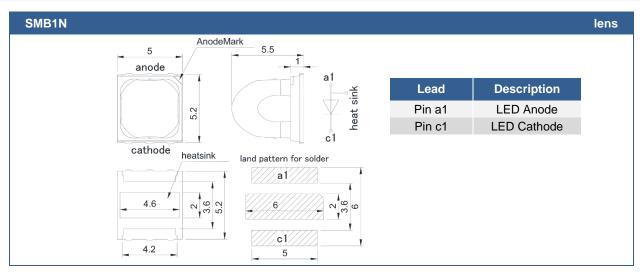
Typical Performance Curves







Outline Dimensions



All Dimensions in mm



Precautions

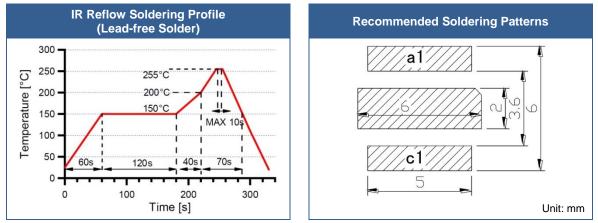
Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.



Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.



Revisions History

Rel.	Rel. Date	Chapter	Modification	Page
A1	2020-09-30	-	Initial release	-

© All Rights Reserved

The above specifications are for reference purpose only and subjected to change without prior notice